

PIC05030CYDQ1 TYPE

●FEATURE

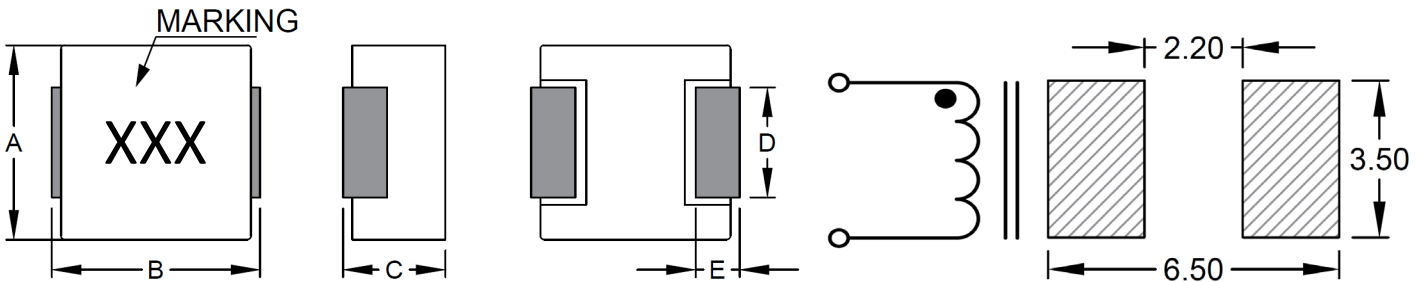
1. Shielded construction, Low EMI
2. High current carrying capacity, Low core losses
3. AEC-Q200 Qualified

●Applications

1. Notebook, server application, High current power supplier

●Shape and Dimension

●Schematics and Land Patterns(mm)



A=5.30±0.20mm ; B=5.70±0.30mm ; C=2.80±0.20mm ; D=3.00±0.20mm ; E=1.20±0.30mm

●Specification

P/N	L (uH)	RDC (mΩ) Typ.	RDC (mΩ) Max.	Isat (A)	Irms (A)
PIC05030CYDQ1-R33M	0.33±20%	2.80	3.40	25.0	21.0
PIC05030CYDQ1-R36M	0.36±20%	2.90	3.50	24.0	20.0
PIC05030CYDQ1-R47M	0.47±20%	3.20	3.90	20.0	19.0
PIC05030CYDQ1-R68M	0.68±20%	4.30	5.20	18.0	17.0
PIC05030CYDQ1-1R0M	1.00±20%	5.60	6.70	16.0	15.0
PIC05030CYDQ1-1R2M	1.20±20%	7.00	8.40	15.3	14.5
PIC05030CYDQ1-1R5M	1.50±20%	8.30	10.0	15.0	14.0
PIC05030CYDQ1-2R2M	2.20±20%	12.0	14.4	12.5	12.0
PIC05030CYDQ1-3R3M	3.30±20%	17.5	21.0	10.5	10.0
PIC05030CYDQ1-4R7M	4.70±20%	27.0	32.4	10.0	8.50
PIC05030CYDQ1-5R6M	5.60±20%	37.0	44.4	8.00	7.20
PIC05030CYDQ1-6R8M	6.80±20%	41.5	50.0	7.50	6.60
PIC05030CYDQ1-8R2M	8.20±20%	52.0	62.4	7.30	5.80
PIC05030CYDQ1-100M	10.0±20%	65.0	78.0	6.80	5.00

Note1. Measurement frequency of Inductance value : at 100kHz, 1.0V

Note2. Measurement ambient temperature of L, DCR and IDC : at 25°C

Note3. Isat: DC current at which the inductance drops 30%(Typ.) from its value without current

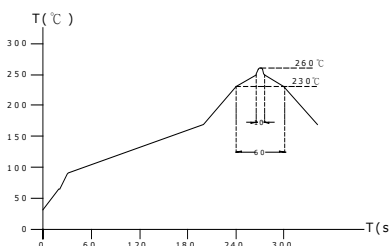
Note4. Irms: Average current for 40°C temperature rise from 25°C ambient(Typ.)

Note5. Packaging: Taping ; Quantity: 2000 Pieces/Reel

GENERAL CHARACTERISTICS

1. Operating temperature range: -55 TO + 125°C (Includes temperature when the coil is heated)
2. High temperature exposure(storage) refer MIL-STD-202 Method 108: 1000 hrs at rated operating temperature(e.g. 125°C). Part can be stored for 1000 hrs @125°C. Unpowered. Measurement at 24±4 hours after test conclusion.
3. Temperature cycling refer JESD22 Method JA-104: 1000 cycles(-55 TO + 125°C). Measurement at 24±4 hours after test conclusion. 30 min maximum dwell time at each temp. extreme. 1 min. maximum transition time.
4. Biased Humidity refer MIL-STD-202 Method 103: 1000 hours 85°C/85%RH. Unpowered. Measurement at 24±4 hours after test conclusion.
5. Operational Life refer MIL-PRF-27: 1000 hrs. at 125 °C tested. Measurement at 24±4 hours after test conclusion.
6. External Visual refer MIL-STD-883 Method 2009: Inspect device construction, marking and workmanship.
7. Physical Dimension refer JESD22 Method JB-100: Verify physical dimensions to the applicable device detail specification.
8. Resistance to Solvents refer MIL-STD-202 Method 215: Add aqueous wash chemical - OKEM clean or equivalent.
9. Mechanical Shock refer MIL-STD-202 Method 213: Figure 1 of Method 213. Condition C.
10. Vibration refer MIL-STD-202 Method 204: 5g;s for 20 minutes, 12 cycles each of 3 orientations. Test from 10-2000 Hz.
11. Resistance to soldering Heat refer MIL-STD-202 Method 210: Condition B No pre-heat of samples. Single wave solder-procedure 2 for SMD and procedure 1 for leaded with solder within 1.5mm of device body.
12. ESD refer AEC-Q200-002 or ISO/DIS 10605: Direct contact discharge 2kV.
13. Solderability refer J-STD-002: For both Leaded & SMD. Magnification 50X. Conditions: Leaded, Method A@235°C ,category 3 ; SMD, a)Method B, 4hrs@125°C dry heat @235°C, b)Method B@215°C category 3., c)Method D category 3@260°C
14. Electrical Characterization refer spec: Show Min, Max Mean and Standard deviation at room from Min and Max temperature.
15. Flammability refer UL-94: V-0 or V-1 Acceptable.
16. Board Flex refer AEC-Q200-005: 60 sec minimum holding time.
17. Terminal Strength(SMD) refer AEC-Q200-006
18. Reflow profile recommend:

Lead-free heat endurance test



Lead-free the recommended reflow condition

